The market outlook for SiC devices is promising. According to Yole Développement, it is expected to grow from $716M to $3B for the period 2020-2025. Nevertheless, the technical panorama of SiC devices is still varying, and every manufacturer has its own solutions to die design and packaging integration. This leads to strong competition, which will accelerate technical innovation and lower prices. Moreover, SiC business models are still very different. We are seeing (and will continue to see) a restructuring of the supply chain driven by the main cost factors.

Since the commercialization of the first SiC device in 2001, the performance of SiC devices and the value that they add have been gradually proven. Their price has also become increasingly acceptable to end-users.

SiC transistors still have some technical and commercial challenges to face, despite the value they add. These include the wafer price and the complexity of some process steps specifically, SiC epitaxy, SiC etching, and high-temperature implantation. These challenges still hinder SiC adoption on a large commercial scale.

In this report, System Plus Consulting presents an overview of the state-of-the-art of SiC transistors. We cover 37 SiC transistors (33 SiC MOSFETs and 4 SiC JFETs) from six voltage classes: 650V, 900V, 1000V, 1200V, 1700V, and 3300V. The transistors are from Rohm, STMicroelectronics, Wolfspeed, Infineon, Littelfuse, IXYS (part of Littelfuse), onsemi, Microsemi, UnitedSiC (now Qorvo), GeneSiC, and Toshiba, and they target different power applications (including three automotive-qualified devices).

This report provides detailed optical and scanning electron microscope (SEM) pictures of the devices’ packaging and structure, with a focus on transistor design. Also included is an estimated manufacturing cost of the analyzed SiC transistors and their selling prices, providing physical, technological, and manufacturing cost comparisons between them.

COMPLETE TEARDOWN WITH:
- SiC benchmark and technology roadmap
- Detailed optical and SEM photos
- Precise measurements
- Manufacturing process flow
- Supply chain evaluation
- Manufacturing cost analysis
- Estimated selling price
- Comparisons of technology design parameters, performance (figure of merits, current density), and costs (wafer, die, component, and cost per ampere)
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**Tom Herve** has joined System Plus Consulting as a Microelectronic Laboratory Technician in order to strengthen the laboratory team. In 2020, Tom was graduated from the University of Blois where he obtained a Technical degree (DUT) in Physical Measurements. He previously worked on different subject among which precipitation of zinc oxide.

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